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HiKey 960 Development Board - 4GB RAM Version

SKU 102110117

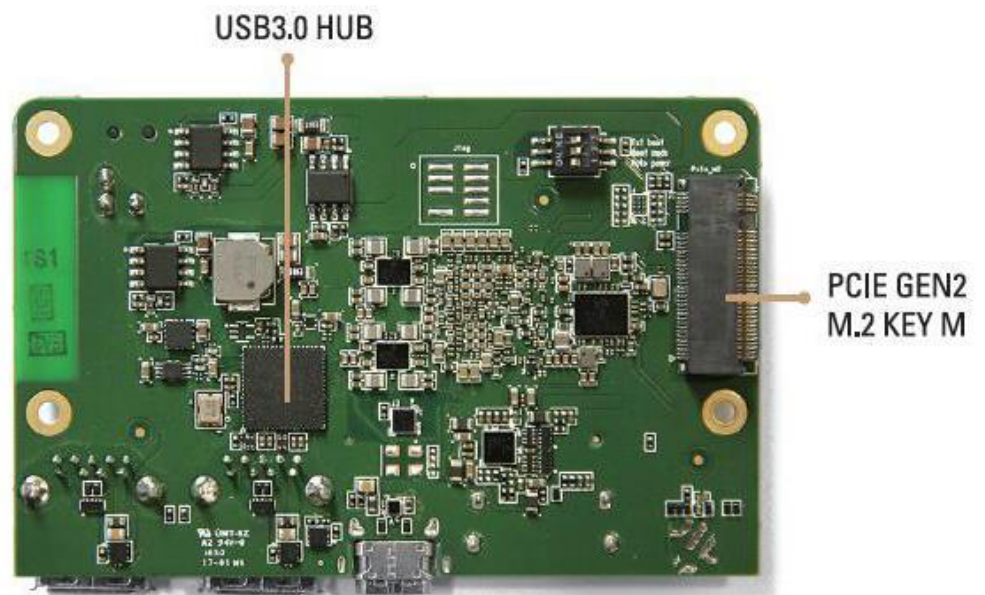
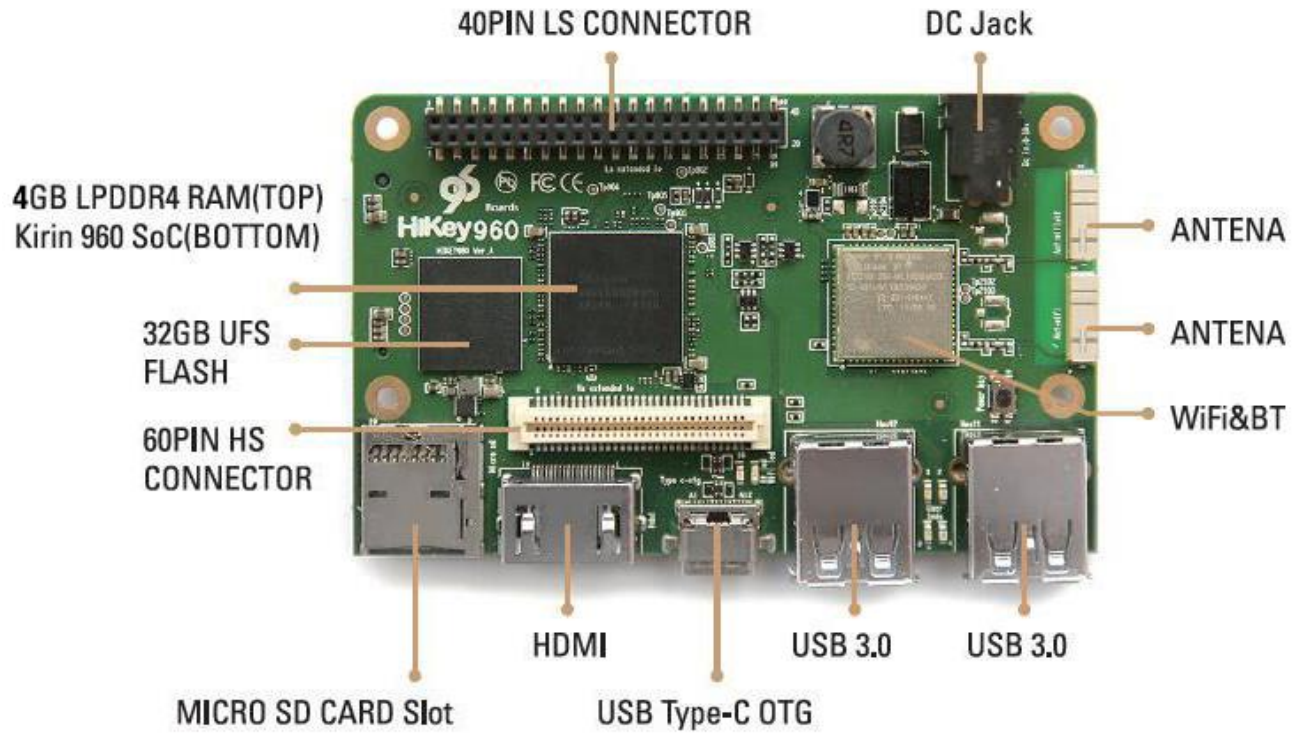
Description

The HiKey 960 is powered by the latest Kirin 960 SoC with four ARM Cortex-A73 CPUs (up to 2.3GHz) and four ARM Cortex-A53 CPUs (up to 1.8GHz) configured according to the big.LITTLE architecture. The integrated Mali™-G71 MP8 GPU in the Kirin 960 SoC gives the HiKey 960 high performance image processing abilities. With 4GB LPDDR4 memory and 32GB UFS flash on board, the HiKey 960 can be used for most embedded applications.

The HiKey 960 has updated the USB Type-A host from USB2.0 to USB3.0 compared to the original HiKey board. In order to enhance the expansion ability, the HiKey 960 includes a PCIe Gen2 on M.2 M Key connector to enable PCIe device connection. The HiKey 960 also includes an updated WiFi module supporting 2.4GHZ single band to 2.4- and 5.0GHz dual band with two antennas.

Android support for the HiKey 960 will be enabled through Android Open Source Project (AOSP). Additional software support will be added through collaboration between Huawei, Linaro and the community.

Hardware layout



Technical Details

Dimensions	85mm x 55mm x 25mm
Weight	G.W 60g
Battery	Exclude
Storage	32GB UFS flash storage; MicroSD card slot (SD3.0, SDR104, up to 2TB)
PCIE	PCIE Gen2 on M.2 M Key connector
Wireless	WiFi (2.4- and 5-GHz dual band with two antennas); Bluetooth 4.1
USB	2 x USB 3.0 type A (host mode only); 1 x USB 2.0 type C OTG
Display	1 x HDMI 1.4 (Type A - full, up to FHD 1080P); 1 x 4L-MIPI DSI (Supports up to 3840 * 2400 @ 60Hz dual MIPI DSI interface LCD screen)
Video	4K @30fps H.265/H264 video hardware encoder; H265\HEVC MP/High Tier, Main/High Tier, H.264 BP/MP/HP, MPEG 1/2/4, VC-1, VP6/8, RV8/9/10, DIVX, H265 up to 4K @60fps video hardware decoder
Audio	HDMI output; 1 x Tensilica HiFi3.0 DSP audio subsystem
Camera	1 x WiFi activity LED (Yellow); 1 x BT activity LED (Blue); 4 x User LEDs (Green)
Button	Power Button : Button Power on/off & Reset the system
Power Source	Recommend a 12V@2A adapter with a DC plug which has a 4.75mm outer diameter and 1.7mm center pin with standard center-positive (EIAJ-3 Compliant)

OS Support	AOSP
SoC	Kirin 960 SoC
CPU	4*Cortex A73 (up to 2.3GHz) + 4*Cortex A53 (up to 1.8GHz) Big.LITTLE CPU architecture
GPU	ARM Mali G71 MP8, up to 900MHz
RAM	4GB LPDDR4 SDRAM @ 1866MHz
PMU	Hi6421GWCV530 Hi6422GWCV211 Hi6422GWCV212

Part List

HiKey 960 Development Board - 4GB RAM Version	1
Heat sink	1
Instruction Manual	1
Audio extension line	1

Documents

- [Tools for flash OS](#)
- [AOSP build instruction](#)
- [AOSP Support](#)
- [Board configuration for AOSP](#)
- [AOSP kernel](#)
- [Documentation](#)